FIG.1

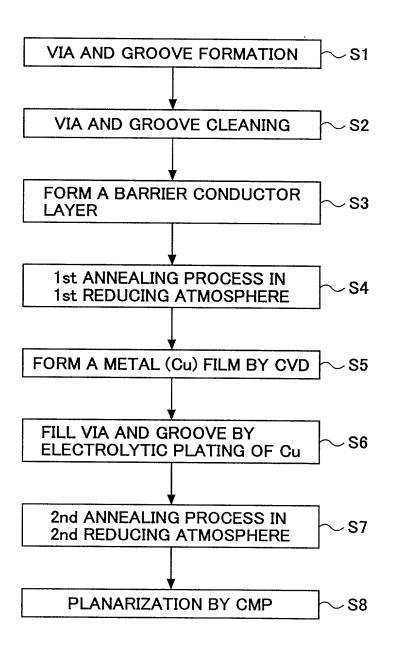


FIG. 2

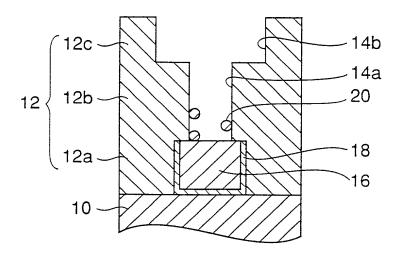


FIG. 3

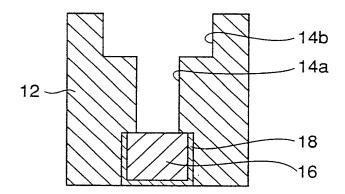


FIG. 4

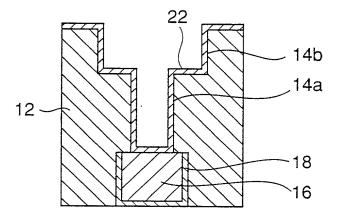


FIG. 5

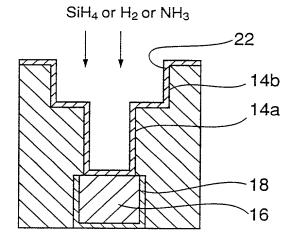


FIG. 6

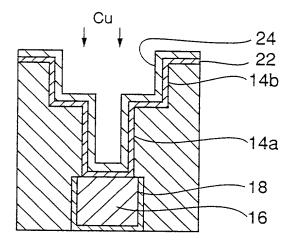


FIG. 7

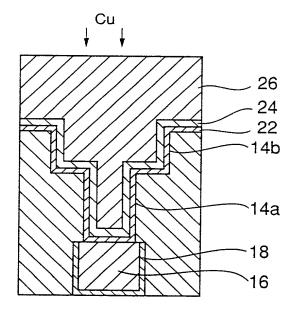


FIG. 8

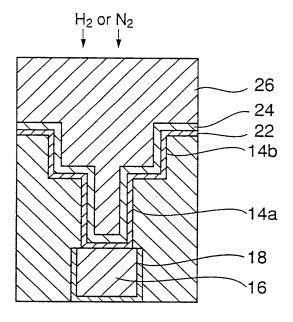
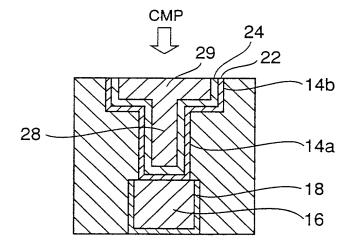


FIG. 9



**FIG.10** 

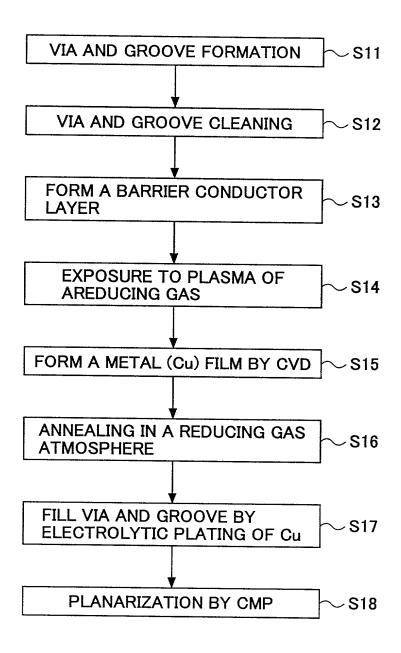


FIG. 11

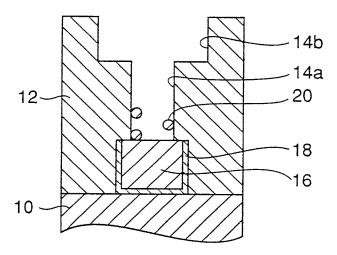


FIG. 12

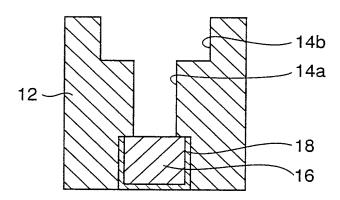


FIG. 13

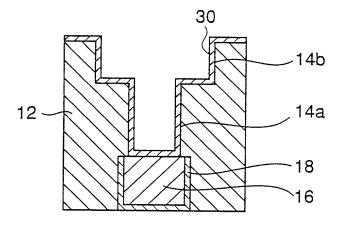


FIG. 14

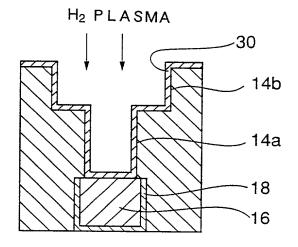


FIG. 15

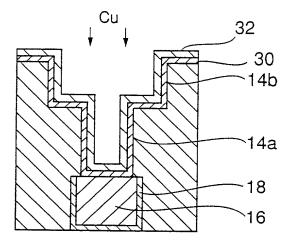


FIG. 16

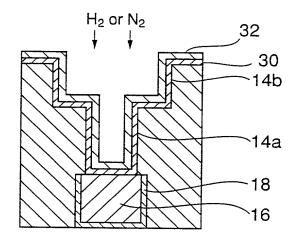


FIG. 17

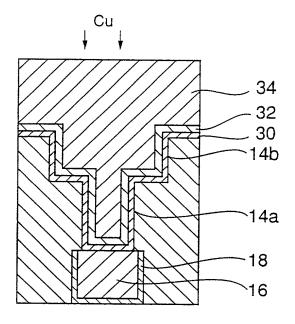
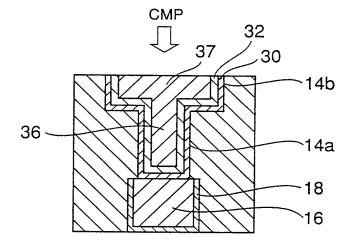


FIG. 18



## FIG.19

			Control of the Contro		***************************************	The same of the last of the la		
	BARRIER CONDUCTOR	METAL FILM	1st ANNEAL GAS	1st ANNEAL 2nd ANNEAL PLASMA GAS GAS	PLASMA GAS	TAPE TEST	STRENGTH TEST (MPa)	
	TaN(PVD)	(CVD)	εHN	H <sub>2</sub>	I	0	68	
EXP2	TaN(PVD)	Cu(CVD)	SiH4	H <sub>2</sub>	-	0	74	
EXP3	TaN(PVD)	Cu(CVD)	H2	H <sub>2</sub>	I	0	69	
EXP4	WN(CVD)	Cu(CVD)	SiH4	H2	I	0	64	
EXP5	WN(CVD)	Cu(CVD)	1	I	H <sub>2</sub>	0	75	
COMP1	TaN(PVD)	(GVD)	I	I	1	×	31	
COMP2	TaN(PVD)	Cu(CVD)	1	H2	ı	×	44	
COMP3	TaN(PVD)	Cu(CVD)	NH3	1	I	×	1	
COMP4	TaN(PVD)	(GVD)nO	SiH4	I	1	×	I	
COMP5	TaN(PVD)	(GVD)nO	H2	l	I	×		
	TaN(PVD)	Cu(PVD) +Cu(CVD)	-	H <sub>2</sub>	l	0	69	

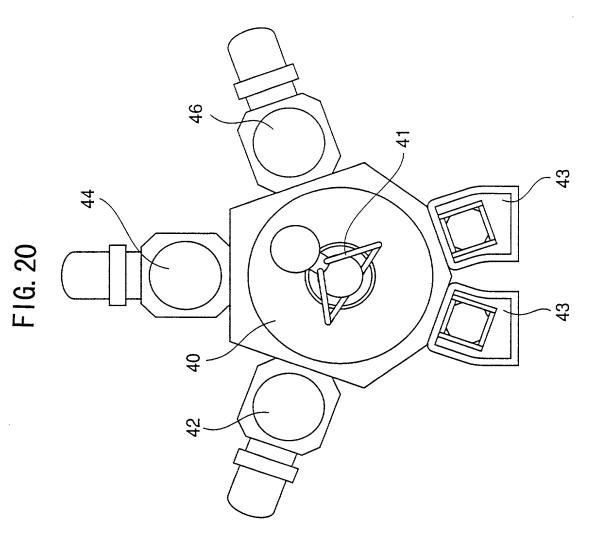
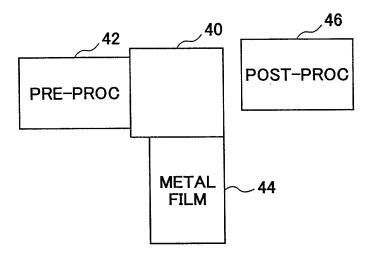
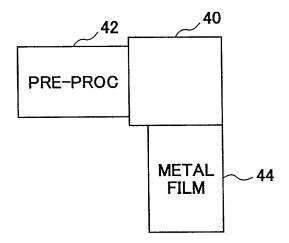


FIG.21



**FIG.22** 



**FIG.23** 

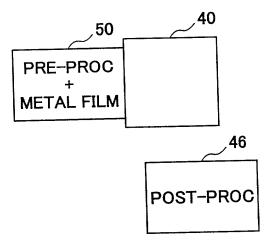
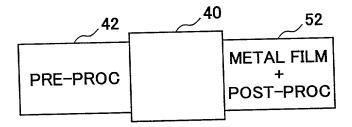


FIG.24



**FIG.25** 

